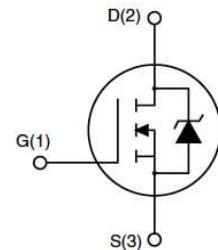


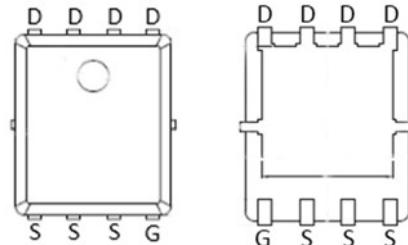
Features

- 60V,50A
- $R_{DS(ON)} < 7.2\text{m}\Omega$ @ $V_{GS}=10\text{V}$ TYP: $5.3\text{m}\Omega$
- $R_{DS(ON)} < 10.5\text{m}\Omega$ @ $V_{GS}=4.5\text{V}$ TYP: $7.6\text{m}\Omega$
- Low RDS(ON)
- 100% UIS Tested
- RoHS compliant (Note 1)
- Halogen-free



Applications

- Battery Management System
- Motor Drivers
- DC-DC Converter



PDFN5X6

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity (PCS)
G072N06G	APG072N06G	PDFN5X6	-	-	5000

ABSOLUTE MAXIMUM RATINGS ($T_a=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	60	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ($T_C = 25^\circ\text{C}$) ^(2,3)	I_D	50	A
Continuous Drain Current ($T_C = 100^\circ\text{C}$) ^(2,3)	I_D	36	A
Pulsed Drain Current ^(1,2,3)	I_{DM}	200	A
Single Pulsed Avalanche Energy ($V_{DD} = 30\text{V}, L = 0.5\text{mH}$)	E_{AS}	90	mJ
Drain Power Dissipation	P_D	30	W
Thermal Resistance from Junction to Case ⁽²⁾	$R_{\theta JC}$	4.2	$^\circ\text{C}/\text{W}$
Thermal Resistance- Junction to Ambient ⁽²⁾	$R_{\theta JA}$	56	$^\circ\text{C}/\text{W}$
Junction Temperature	T_J	150	$^\circ\text{C}$
Storage Temperature	T_{STG}	-55~+150	$^\circ\text{C}$

Notes:

1. Pulse width $\leq 300\ \mu\text{s}$, duty cycle $\leq 2\ %$
2. Surface Mounted on n 1 in2 pad area, $t \leq 10\ \text{sec}$.
3. Limited by bonding wire

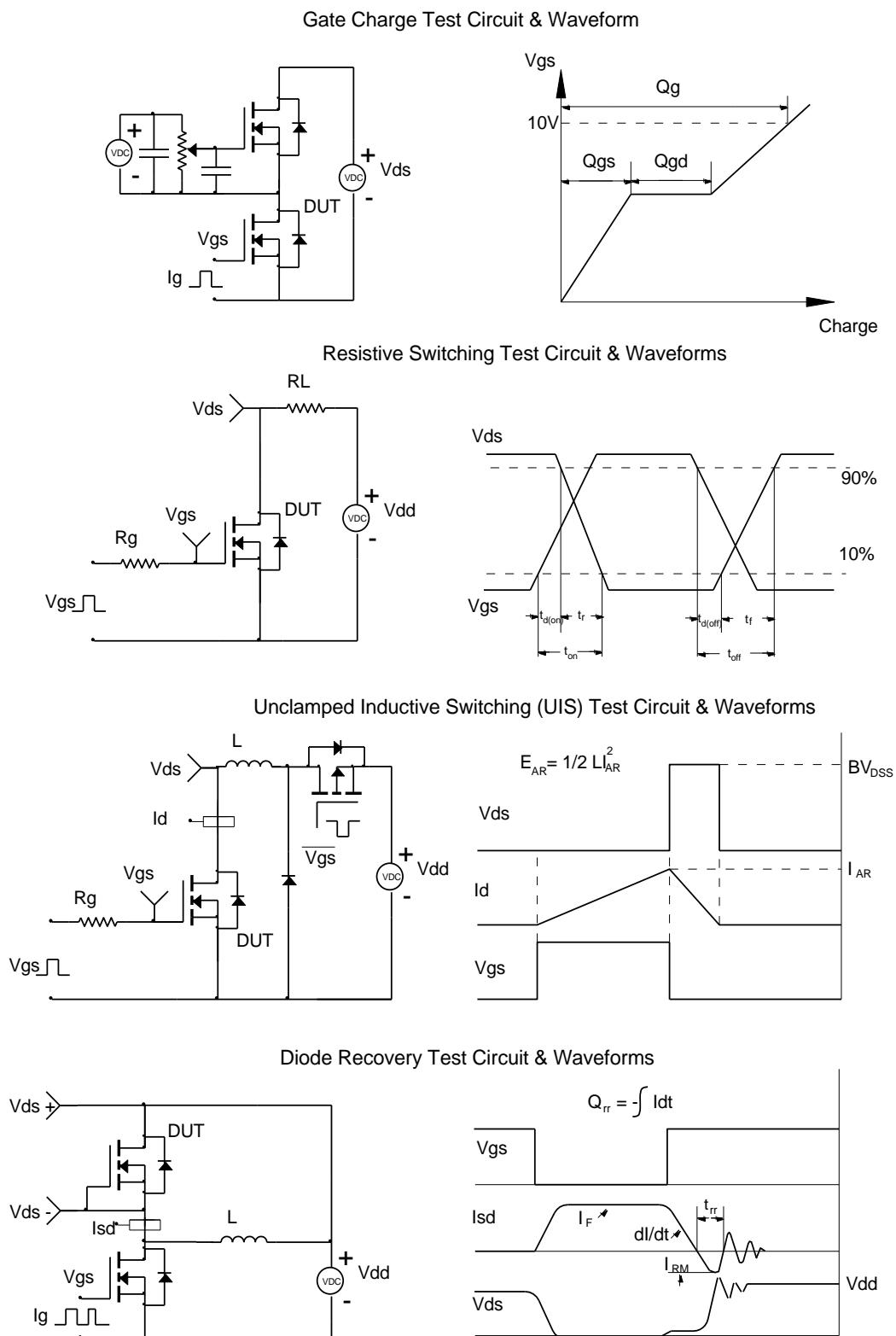
MOSFET ELECTRICAL CHARACTERISTICS($T_a=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Type	Max	Unit
Static Characteristics						
Drain-source breakdown voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	60	-	-	V
Zero gate voltage drain current	I_{DSS}	$V_{\text{DS}} = 60\text{V}, V_{\text{GS}} = 0\text{V}$	-	-	1	μA
Gate-body leakage current	I_{GSS}	$V_{\text{GS}} = \pm 20\text{V}, V_{\text{DS}} = 0\text{V}$	-	-	± 100	nA
Gate threshold voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	1.0	2.0	3.0	V
Drain-source on-resistance ^(a)	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_D = 20\text{A}$	-	5.3	7.2	$\text{m}\Omega$
		$V_{\text{GS}} = 4.5\text{V}, I_D = 15\text{A}$	-	7.6	10.5	$\text{m}\Omega$
Dynamic characteristics						
Input Capacitance	C_{iss}	$V_{\text{DS}} = 30\text{V}, V_{\text{GS}} = 0\text{V}, f = 1.0\text{MHz}$	-	2013	-	pF
Output Capacitance	C_{oss}		-	492	-	
Reverse Transfer Capacitance	C_{rss}		-	34	-	
Switching characteristics						
Turn-on delay time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 30\text{V}, I_D = 50\text{A}, R_G = 6\Omega, R_L = 1.5\Omega, V_G = 10\text{V}$	-	16	-	ns
Turn-on rise time	t_r		-	89	-	
Turn-off delay time	$t_{\text{d}(\text{off})}$		-	47.5	-	
Turn-off fall time	t_f		-	111	-	
Total Gate Charge	Q_g	$V_{\text{DS}} = 30\text{V}, I_D = 50\text{A}, V_{\text{GS}} = 10\text{V}$	-	32	-	nC
Gate-Source Charge	Q_{gs}		-	4.3	-	
Gate-Drain Charge	Q_{gd}		-	5.2	-	
Source-Drain Diode characteristics						
Diode Forward voltage ^(a)	V_{SD}	$T_J = 25^\circ\text{C}, V_{\text{GS}} = 0\text{V}, I_S = 20\text{A}$	-	-	0.7	V
Diode Forward current	I_S	$T_C = 25^\circ\text{C}$	-	-	45	A
Body Diode Reverse Recovery Time	trr	$T_J = 25^\circ\text{C}, IF = 20\text{A}, di/dt = 100\text{A}/\mu\text{s}$		38		ns
Body Diode Reverse Recovery Charge	Qrr	$T_J = 25^\circ\text{C}, IF = 20\text{A}, di/dt = 100\text{A}/\mu\text{s}$		41		uc

Notes:

- a) Pulse width $\leq 300\ \mu\text{s}$, duty cycle $\leq 2\%$
- b) Guaranteed by design, not subject to production testing

Test Circuit



Typical Performance Characteristics

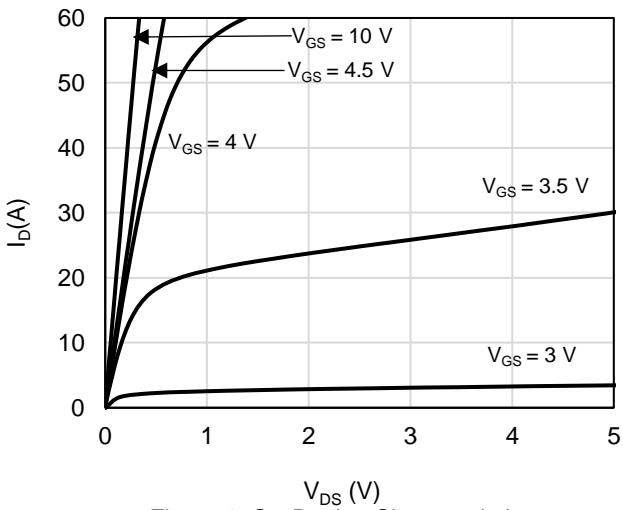


Figure 1: On-Region Characteristics

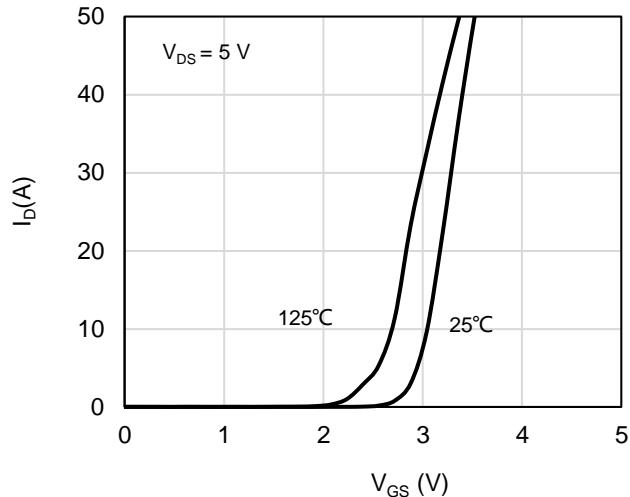


Figure 2: Transfer Characteristics

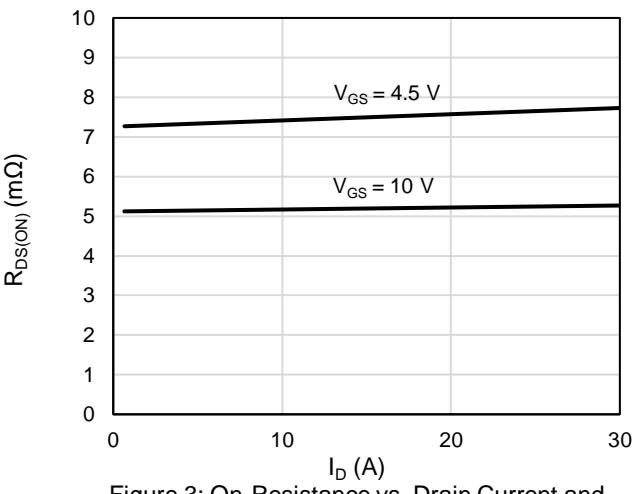


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

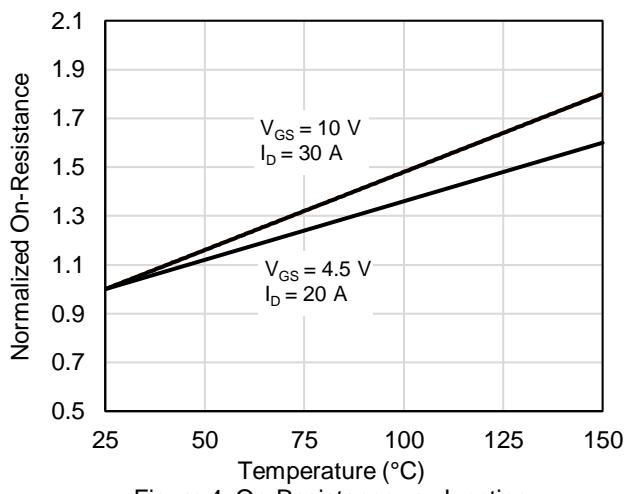


Figure 4: On-Resistance vs. Junction Temperature

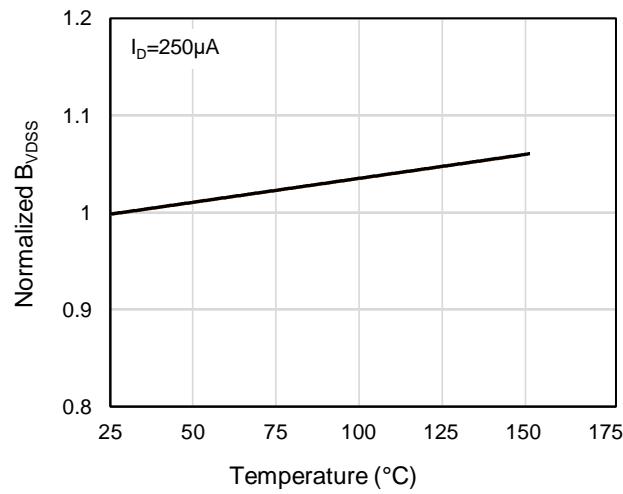


Figure 5: Breakdown Voltage vs. Junction Temperature

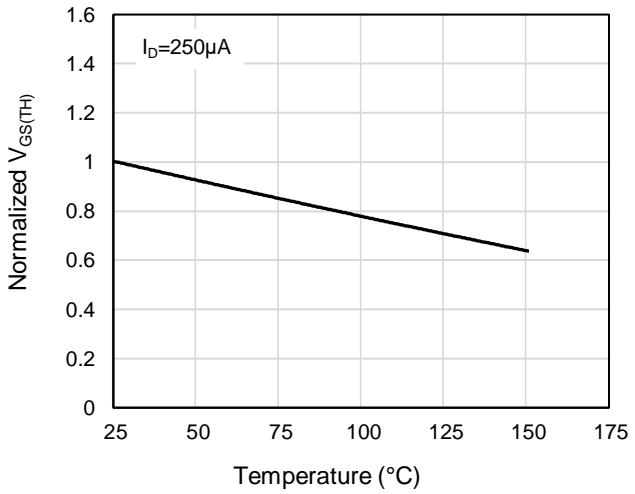


Figure 6: Threshold Voltage vs. Junction Temperature

Typical Performance Characteristics

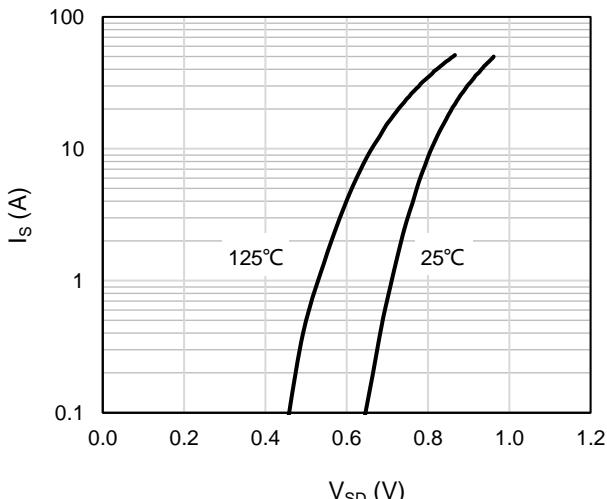


Figure 7: Body-Diode Characteristics

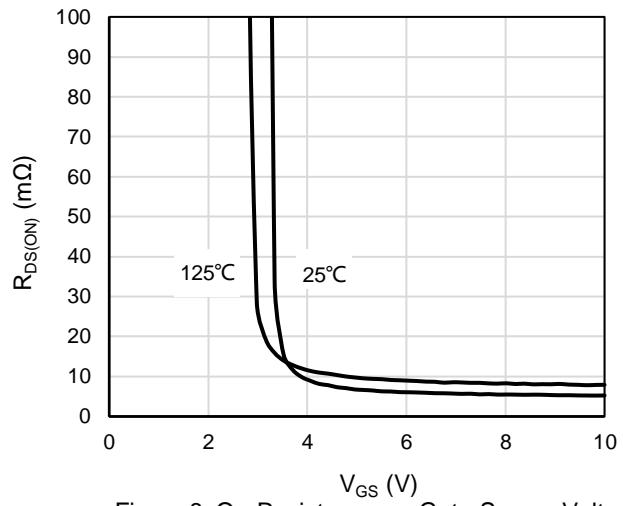


Figure 8: On-Resistance vs. Gate-Source Voltage

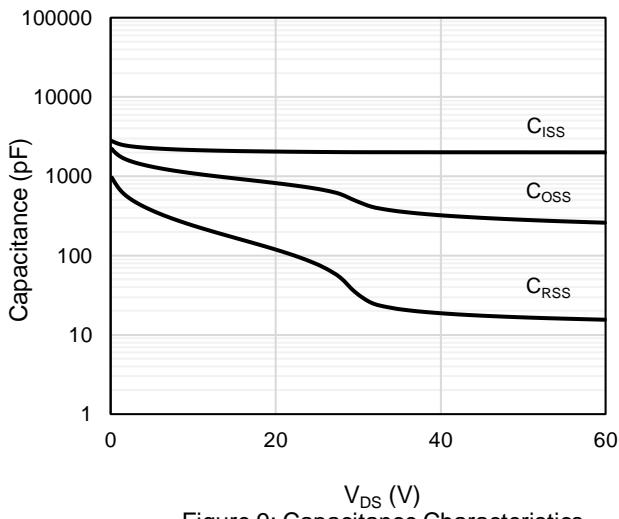


Figure 9: Capacitance Characteristics

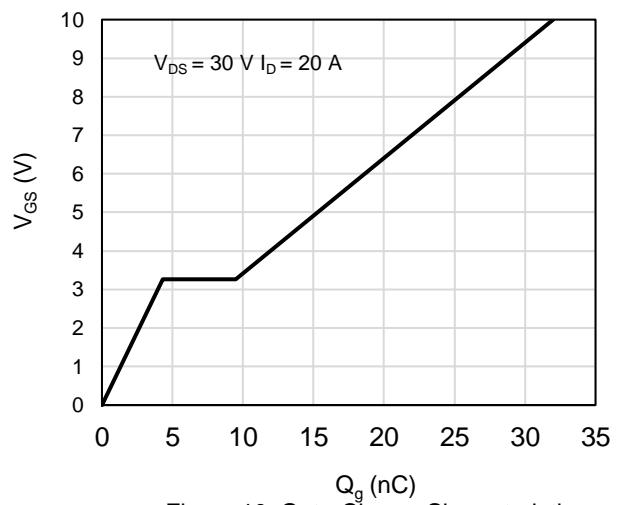


Figure 10: Gate-Charge Characteristics

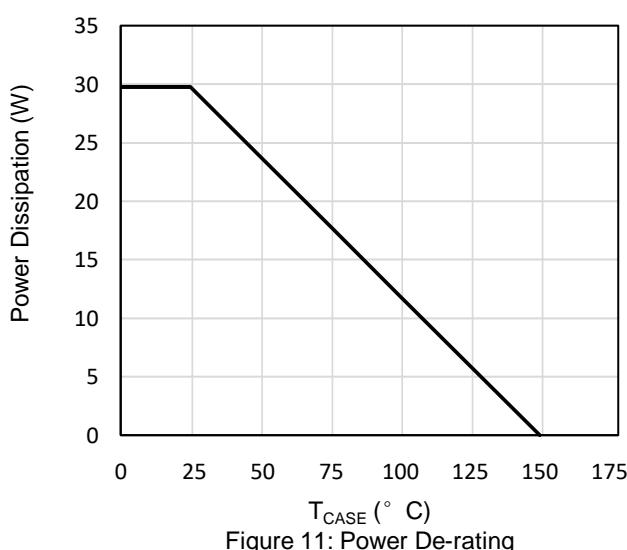


Figure 11: Power De-rating

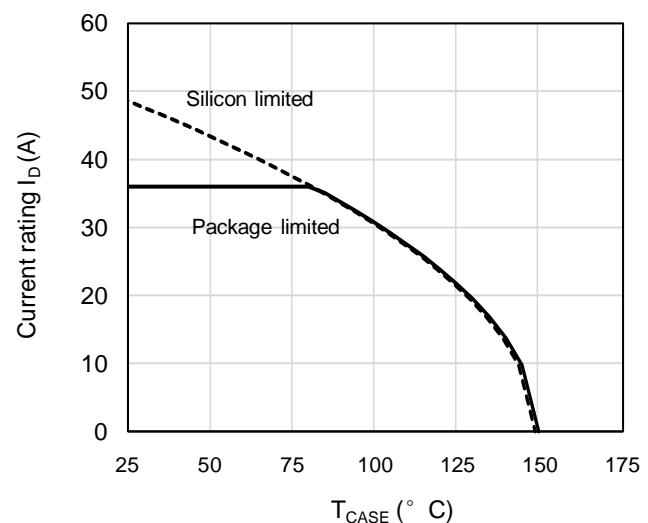
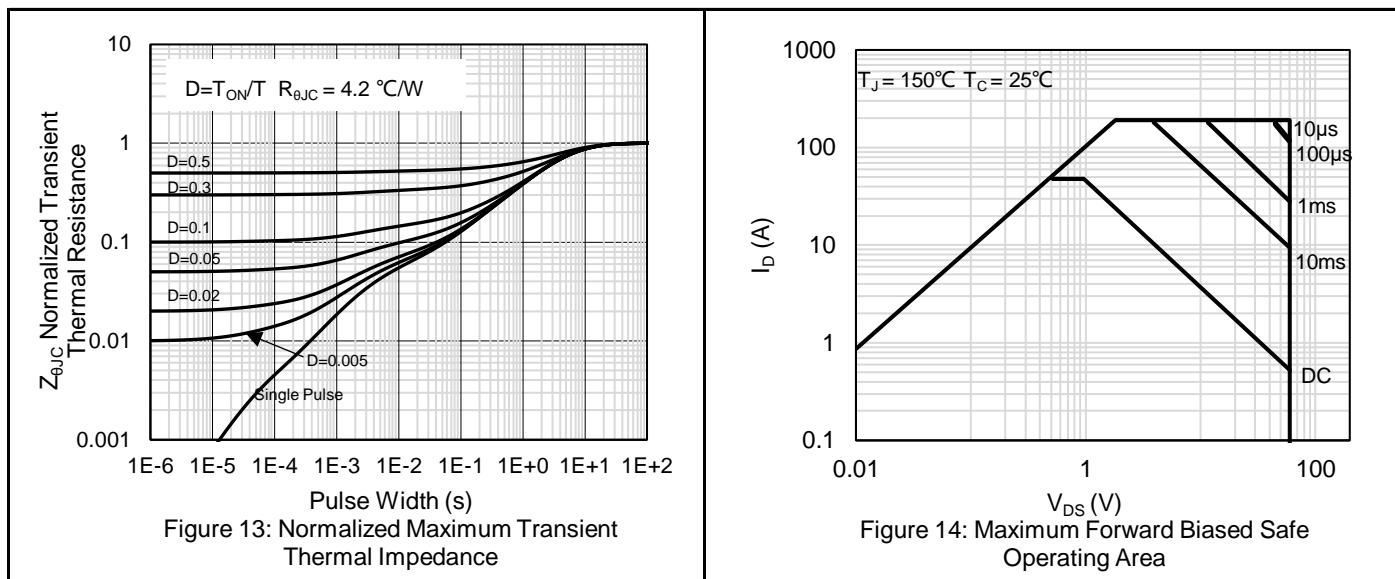
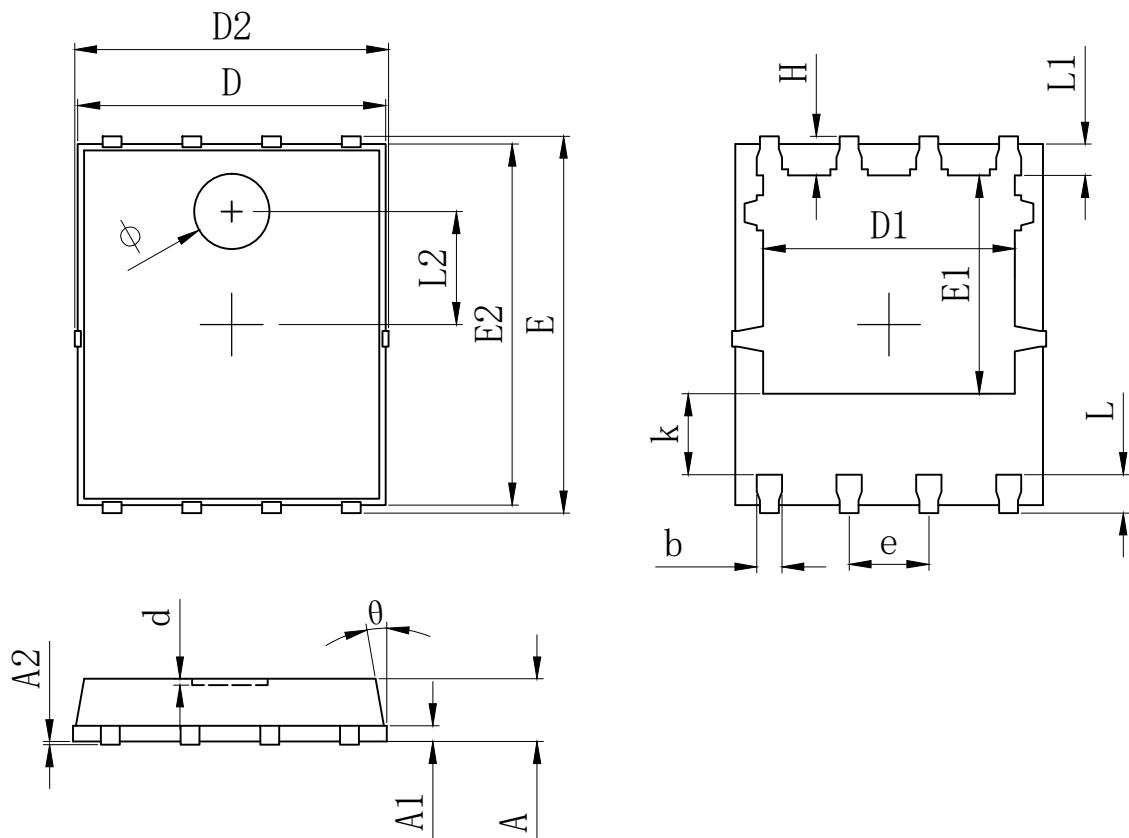


Figure 12: Current De-rating

Typical Performance Characteristics



PDFN5X6 Package Information



SYMBOL	MILLIMETER		
	MIN	Typ.	MAX
A	0. 900	1. 000	1. 100
A1	0. 254 REF.		
A2	0~0. 05		
D	4. 824	4. 900	4. 976
D1	3. 910	4. 010	4. 110
D2	4. 924	5. 000	5. 076
E	5. 924	6. 000	6. 076
E1	3. 375	3. 475	3. 575
E2	5. 674	5. 750	5. 826
b	0. 350	0. 400	0. 450
e	1. 270 TYP.		
L	0. 534	0. 610	0. 686
L1	0. 424	0. 500	0. 576
L2	1. 800 REF.		
k	1. 190	1. 290	1. 390
H	0. 549	0. 625	0. 701
θ	8°	10°	12°
ϕ	1. 100	1. 200	1. 300
d			0. 100